

2.5G BASE-T Magnetics Modules with PoE*

Option MODEL NO.: XF-GD502X001N-NT1

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C/3~5 sec

Suitable for End-span POE+applications with 1A current capability

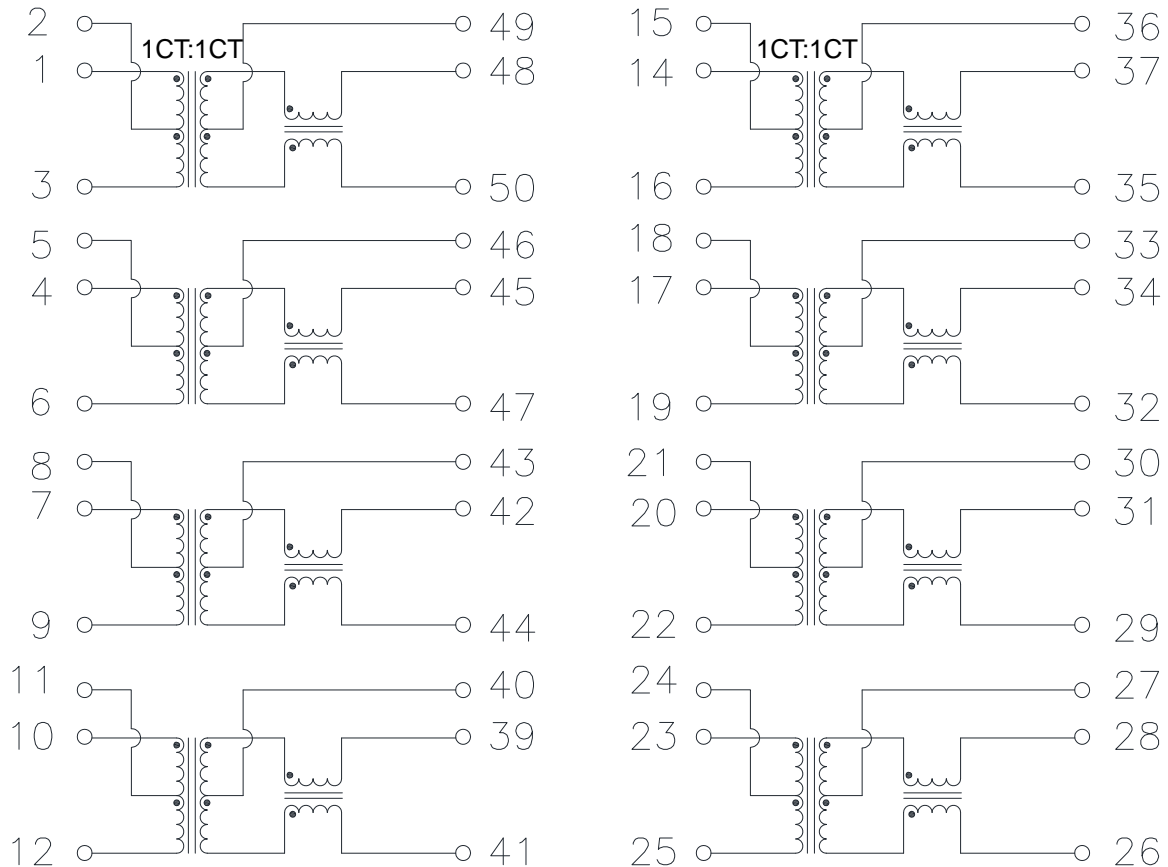
Specifications @ 25°C

OPERATION TEMP : -0°C ~ + 70°C

OCL: 350uH MIN @100KHz 100mV 8mA VDC

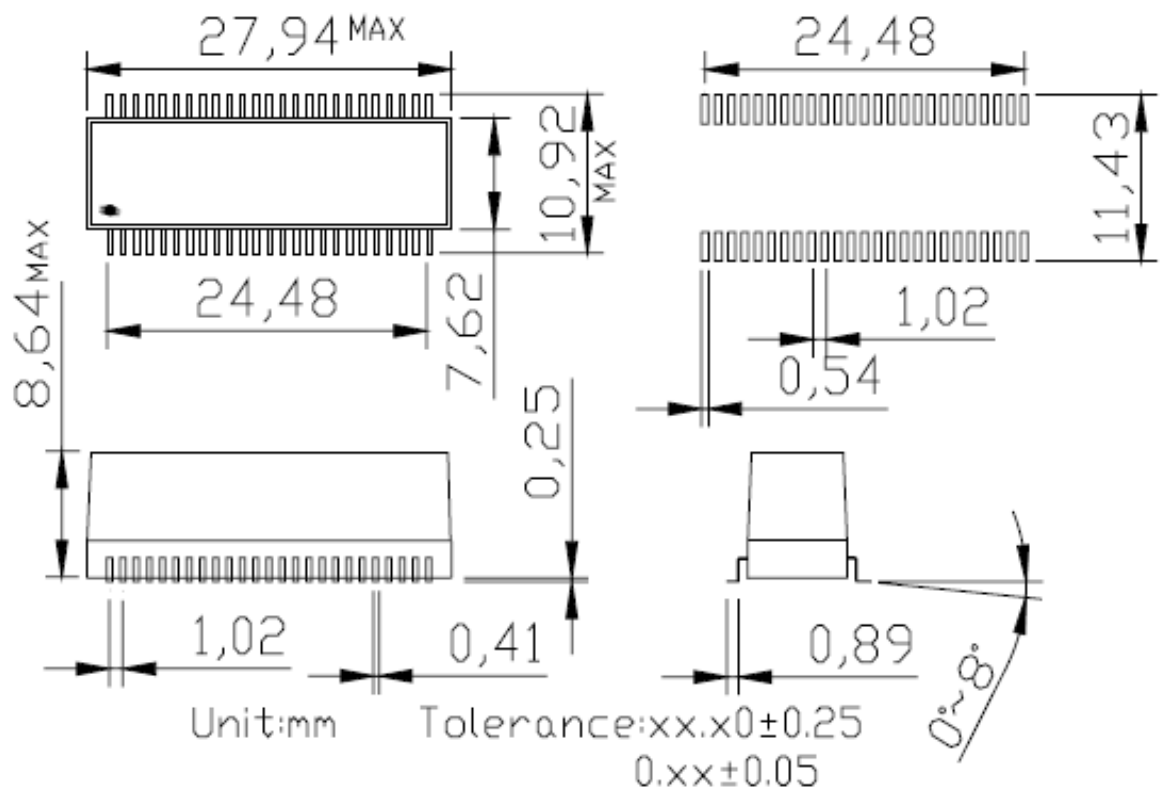
Insertion Loss (dB MAX) MHz			Return Loss (dB MIN) MHz			Crosstalk (dB MIN) MHz		DCMR (dB MIN) MHz		DCR (Ω MAX)	Hi-Pot (Vrms MIN)
1~100	100~125	125~250	1~40	40~100	100~125	1~100	100~125	1~100	100~125		
-1.0	-1.5	-2.5	-16	-10	-6	-30	-25	-30	-25	1.4	1500

SCHEMATIC:

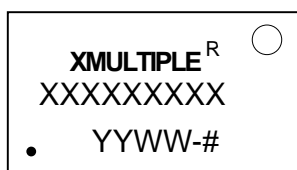


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DIMENSION: mm
TOLERANCE: ±0.25



Marking :



Remark:
XMULTIPLE=LOGO
XXXXXXXXXX=PART NUMBER
YYWW DATE CODE , YY=YEAR · WW=WEEK
#= Control Code

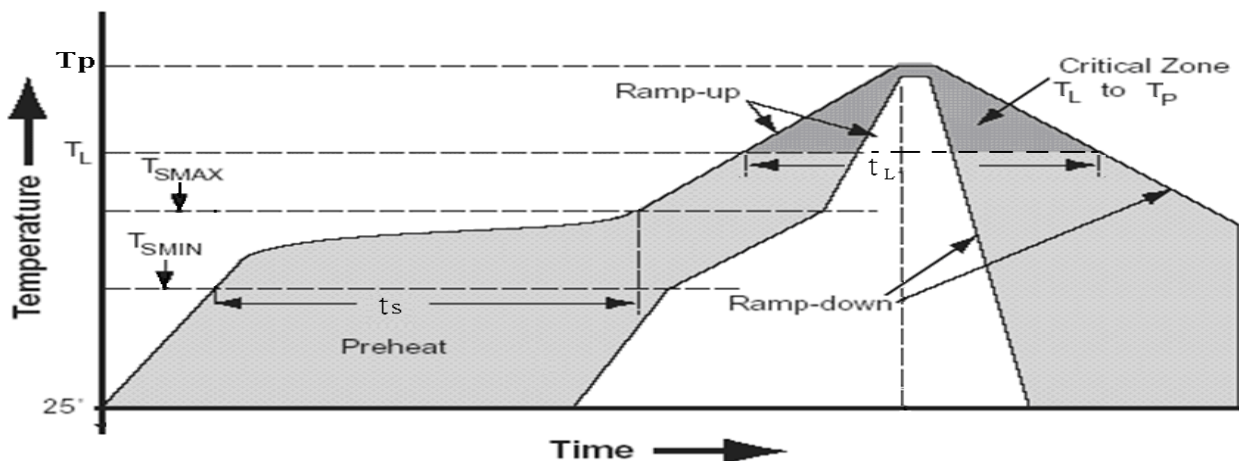
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Solder Reflow profile for Lead-Free packages. Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (t_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	200 °C 60-90 sec	
Peak Temperature (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

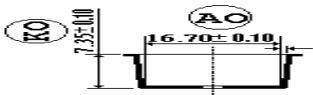
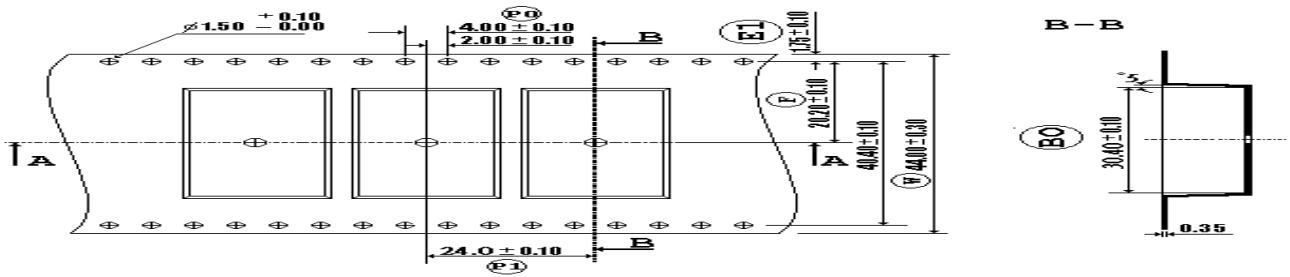
Profile



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PACKING	
1.	Tape & Reel : 350pcs / Reel , 1750pcs / Carton
2.	Dry Pack : 1pcs Product Description:(5g Silica Gel Desiccant) PH: 4-8 Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3.	Reel Packed By Vacuum
4.	Seal Per Jedec

Packing:



A-A

DIMENSION	W	A0	B0	K0	E	F
SPEC	44.0	16.7	30.4	7.35	1.75	20.2
	+/- 0.3	0.1	0.1	0.1	0.1	0.1
DIMENSION	P	P0	P2	D	D1	T
SPEC	24.0	4.0	2.0	1.5	2.0	0.35
	+/- 0.1	0.1	0.1	(MIN)	(MIN)	0.05

Tape & reel-----350/reel
Tube-----16/tube